# 10th MiNaPAD

Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum

## June 7-8, 2023 – Grenoble, France

# Call for extended abstracts

**Extended Abstracts (2 pages typical, including graphs, pictures, …) are requested on the following topics :**

**Advanced packaging :**
TSVs, 2,5 & 3D interposers, wafer level packaging, embedded IC packages, SiP, PoP, MEMS packaging, power packaging, advanced substrates, Hybrid bonding, Fan Out wafer and panel level processes.

**Assembly and manufacturing technologies:**
Bonding, advanced dicing, flux, cleaning, dispensing, coating technologies, materials & equipment related to assembly manufacturing and business aspects of the industry.

**Advanced interconnections:**
Flip-chip including ultra-fine pitches approaches, interconnections, IMC studies, bumping techniques (solder bumps, Cu pillars,...) disruptive interconnections, optical connections.

**Emerging & sustainable technologies & applications:**
Flexible/stretchable packaging, nanomaterial for interconnections, green/bio and sustainable technologies for packaging, additive manufacturing, Nano manufacturing.

**Innovative Materials equipment's and processes:**
3D materials, conductive & non-conductive adhesives, underfill, molding, disruptive solder alloys, thermal interface. Innovative equipment for assembly & packaging.

**Packaging & Assembly Reliability:**
Applied reliability for LED, Displays, IoT, MEMS, memories, medical devices, chip-package and package-PCB interaction. Life models, failure analysis techniques & characterizations.

**Imaging & photonics assembly technologies:**
Assembly & packaging technologies for optical and photonics applications : imaging, displays, silicon photonics, optical sensors, high energy physics and medical imaging.

**Thermal/mechanical simulation and characterization:**
Components, boards & system level modelling for : interconnections, interposers, substrates, WLP & embedded packages, power modules, optical packaging, RF and MEMS.

# Practical information

**Organization :**
IMAPS France
Email: imaps.france@orange.fr
Web: www.france.imapseurope.org

**General chair**: Jean-Marc YANNOU (ASE)
**Technical Chairs**:
Sanae BOULAY (NXP),
Jean-Luc DIOT (Assemblinnov),
Romain COFFY (ST Microelectronics),
Jean-Charles SOURIAU (CEA-LETI),
Christophe ZINCK (ASE),
Laurent MENDIZABAL (CEA-LETI),
Alexandre VAL (VALEO).

**Location** : Close to Grenoble Railway Station

WTC / Congress center

5 -7 , place Robert Schuman – BP 1521

38025 Grenoble Cedex 1

FRANCE

**Exhibition area :**

Equipment & Product suppliers in the WTC Atrium during the workshop

# Important dates

**Extended abstracts submission date :**

From **November 24th , 2022 to March 6th , 2023**

Your submission must include the mailing address, business phone number and email address and the content must be without commercial information.

**Address your abstract to :**

**imaps.france@orange.fr**

**Notification of acceptance :**

Authors will be notified of paper acceptance with instructions for presentation **before March 28th, 2023.**

**Presentations :**

Presentation should be ready one day before the workshop and supply to the chairwomen or chairmen of your session.

**Social event :**

Evening dinner & visit on the 7th of June 2023

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